MECHANICAL SPECIFICATIONS
Indium Phosphide can be supplied in as-cut, etched or polished wafer forms. All slices are individually laser scribed with ingot and slice identity to ensure perfect traceability.

ORIENTATION SPECIFICATIONS
Surface orientations are offered to an accuracy of +/- 0.05 degrees using a triple axis X-Ray diffractometer system. Substrates can also be supplied with very precise misorientations in any direction from the growth plane. Higher index substrates of the type (n,1,1) where n = 1,2,3,4,5,6 etc and orientations such as (110) are also available. We also offer wafers with cleaved flats.

SURFACE SPECIFICATIONS
All wafers are offered with high quality epitaxy-ready finishing. Surfaces are characterised by in-house advanced optical metrology techniques which include Surfscan haze and particle monitoring, spectroscopic ellipsometry and grazing-incidence interferometry.

PACKAGING
Polished Wafers
Coin-style wafer shipper, individually sealed in two outer bags in inert atmosphere. Cassette shipments are available on request.

As-cut Wafers
Cassette shipment. (Glassine bag available on request).

‘Process Trial’ wafers
Coin-style wafer shipper, individually sealed in one outer bag.

If you do not see the specification you require, please call for details on +44 (0)1908 210444 or email sales@wafertech.co.uk

Tighter electrical ranges are available on request.